

Title (en)
LAYER COMPOSITE FOR CONNECTING ELECTRONIC COMPONENTS COMPRISING A COMPENSATION LAYER, LINKING LAYERS AND CONNECTION LAYERS

Title (de)
SCHICHTVERBUND ZUM VERBINDEN VON ELEKTRONISCHEN BAUTEILEN UMFASSEND EINE AUSGLEICHSSCHICHT, ANBINDUNGSSCHICHTEN UND VERBINDUNGSSCHICHTEN

Title (fr)
COMPOSITE STRATIFIÉ CONÇU POUR CONNECTER DES COMPOSANTS ÉLECTRONIQUES, COMPRENANT UNE COUCHE DE COMPENSATION, DES COUCHES DE CONNEXION ET DES COUCHES DE LIAISON

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Abstract (en)
[origin: WO2013045345A2] The present invention relates to a layer composite (10), more particularly for connecting electronic components (11, 12) comprising at least one compensation layer (40), at least two linking layers (30) and at least two connection layers (20), wherein the compensation layer (40) is formed from aluminium or molybdenum, an aluminium or molybdenum alloy, from a metal-matrix material composed of aluminium and silicon carbide or composed of aluminium and copper-carbon, or from a copper-molybdenum alloy, wherein a linking layer (30) composed of silver is in each case applied on at least two opposite sides of the compensation layer (40), and wherein a connection layer (20) is in each case applied on the linking layers (30), wherein the connection layers (20) are formed from sinterable and/or sintered metal powder. The invention furthermore relates to a method for forming a layer composite (10) according to the invention, and to a circuit arrangement (100) containing a layer composite (10) according to the invention.

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